

LL12BT1006

List

List.....	1
Package outline.....	2
Features.....	2
Applications.....	2
Mechanical data.....	2
Maximum ratings	2
Electrical characteristics.....	2
Rating and characteristic curves.....	3
Electrical parameters.....	4
Pinning information.....	4
Suggested solder pad layout.....	4
Packing information.....	5
Reel packing.....	6
Suggested thermal profiles for soldering processes.....	6

LL12BT1006

150W Surface Mount TVS Bi-Directional Low Capacitance For ESD Protection-12V

Features

- Protects one I/O .
- Working voltage : 12V.
- Low leakage current.
- Response time is typically < 1ns.
- Provide transient protection:
IEC 61000-4-2 (ESD) Level 4
IEC 61000-4-4 (EFT) 40A (5/50ns)
IEC 61000-4-5 (Lightning) 4A (8/20us)
- We declare that the material of product
compliance with RoHS requirements.
- Suffix "-H" indicates Halogen-free parts, ex.LL12BT1006-H

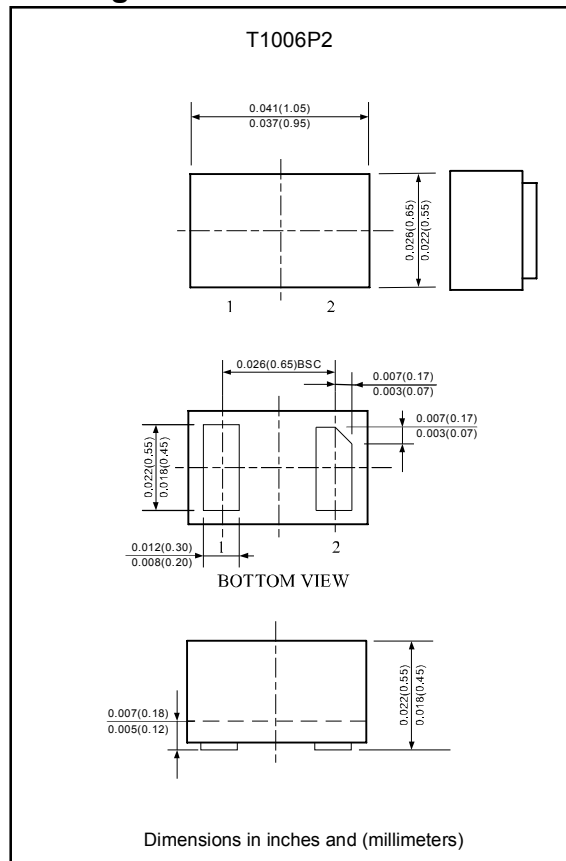
Applications

- Cellular Handsets & Accessories.
- Personal Digital Assistants (PDAs).
- Notebooks & Handhelds.
- Portable Instrumentation.
- Digital Cameras.
- MP3 Players.

Mechanical data

- T1006P2 package
- Molding compound flammability rating : UL94V-0
- Packaging : Tape and reel per EIA 481
- RoHS Compliant
- Weight : Approximated 0.73 mg

Package outline



Maximum ratings (at $T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Peak pulse power ($t_p=8/20\mu\text{s}$)	P_{PP}	150	W
Peak pulse current ($t_p=8/20\mu\text{s}$)	I_{PP}	4	A
Operating temperature	T_J	+125	$^\circ\text{C}$
Storage temperature	T_{STG}	-55 to +125	$^\circ\text{C}$

Electrical characteristics (at $T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Conditions	Symbol	Min.	Typ.	Max.	Unit
Reverse stand-off voltage		V_{RWM}			12	V
Breakdown voltage	$I_T=1\text{mA}$	V_{BR}	13.3			V
Reverse leakage current	$V_{RWM}=12\text{V}$	I_R			200	nA
Clamping voltage	$I_{PP}=1\text{A}, t_p=8/20\mu\text{s}$	V_C		22	25	V
	$I_{PP}=4\text{A}, t_p=8/20\mu\text{s}$			32	35	
Junction capacitance	$V_R=0\text{V}, f=1\text{MHz}$	C_j		0.6	0.8	pF

Note1 : ESD pulse waveform according to IEC 61000-4-2, see Table1 and Figure1

Note2 : ESD tests setup Figure2.

Note3 : The clamping voltage data is taken with a 100x attenuator.

Rating and characteristic curves(LL12BT1006)

Figure 1: Peak Pulse Power vs. Pulse Time

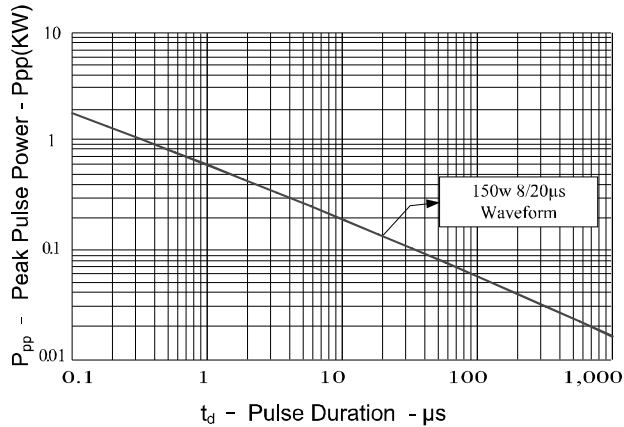


Figure 2: Power Derating Curve

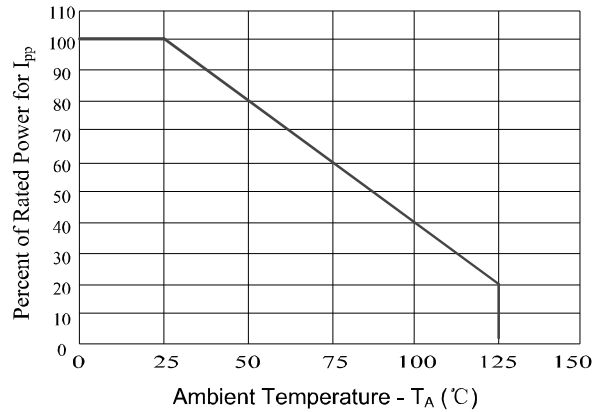


Figure 3: Clamping Voltage vs. Peak Pulse Current

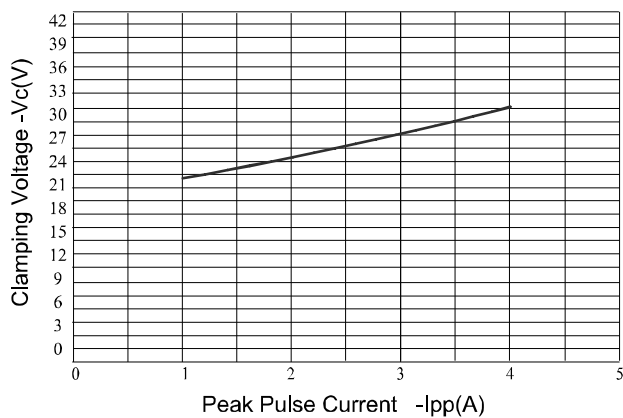


Figure 4: Normalized Junction Capacitance vs. Reverse Voltage

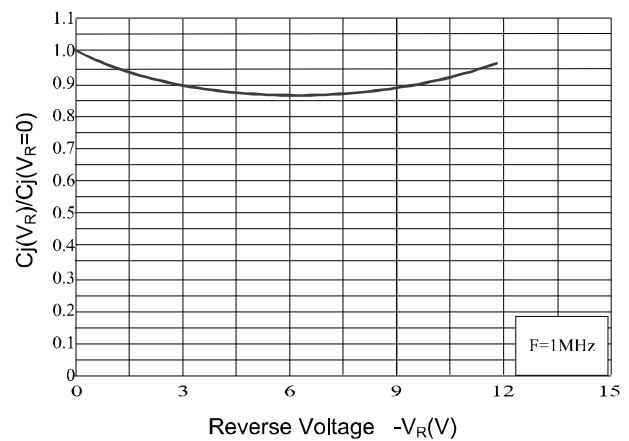
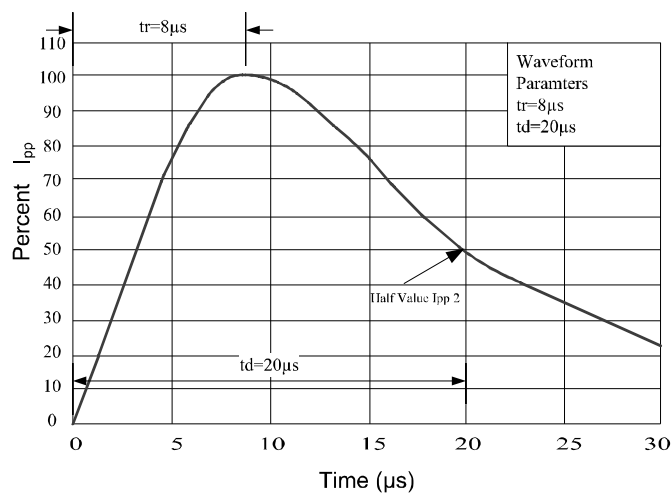


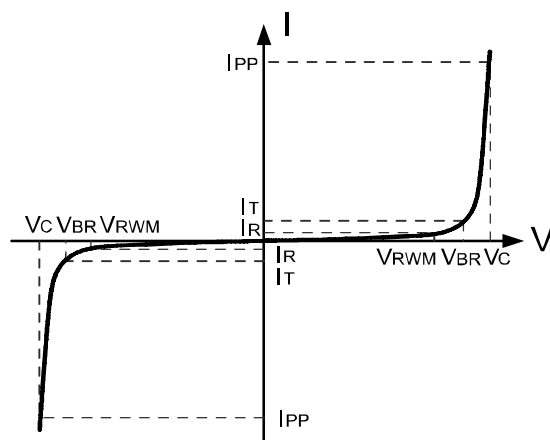
Figure 5: 8/20 μs Pulse Waveform



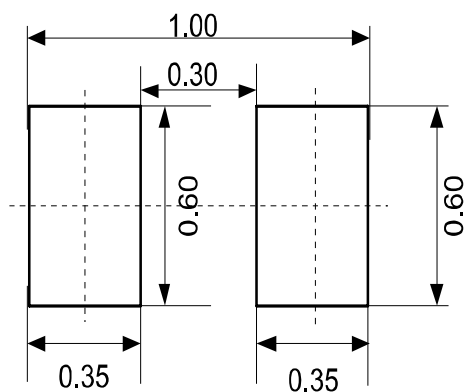
LL12BT1006

Electrical Parameters ($T_A=25^{\circ}\text{C}$)

Symbol	Parameter
I_{PP}	Reverse Peak Pulse Current
V_C	Clamping Voltage @ I_{PP}
V_{RWM}	Reverse Stand-Off Voltage
I_R	Reverse Leakage Current @ V_{RWM}
V_{BR}	Breakdown Voltage @ I_T
I_T	Test Current

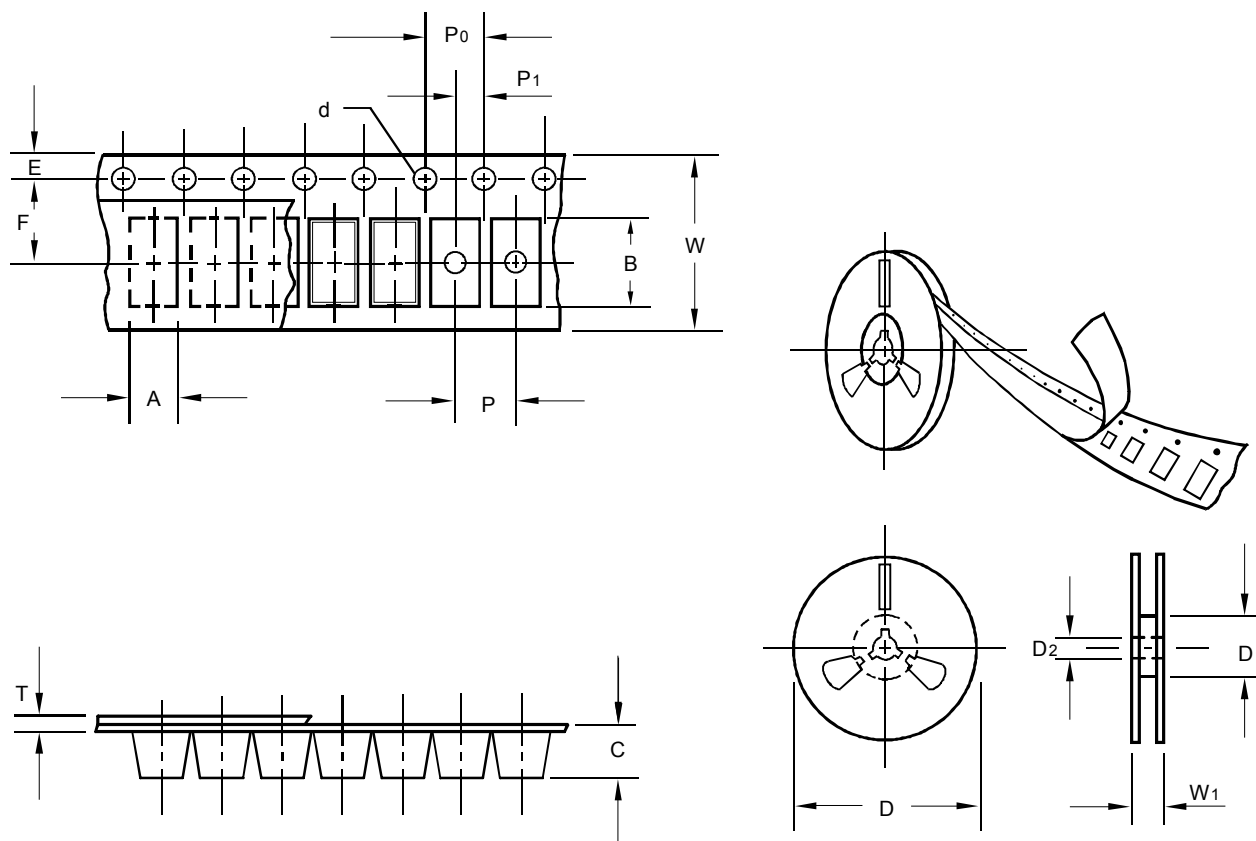
**Pinning information**

Marking Code	Symbol
NN	

Suggested solder pad layout

LL12BT1006

Packing information



unit:mm

Item	Symbol	Tolerance	T1006P2
Carrier width	A	0.1	0.66
Carrier length	B	0.1	1.15
Carrier depth	C	0.1	0.66
Sprocket hole	d	0.1	1.50
13" Reel outside diameter	D	2.0	-
13" Reel inner diameter	D1	min	-
7" Reel outside diameter	D	2.0	178.00
7" Reel inner diameter	D1	min	55.00
Feed hole diameter	D2	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	3.50
Punch hole pitch	P	0.1	2.00
Sprocket hole pitch	P0	0.1	4.00
Embossment center	P1	0.1	2.00
Overall tape thickness	T	0.1	0.23
Tape width	W	0.3	8.00
Reel width	W1	1.0	9.50

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

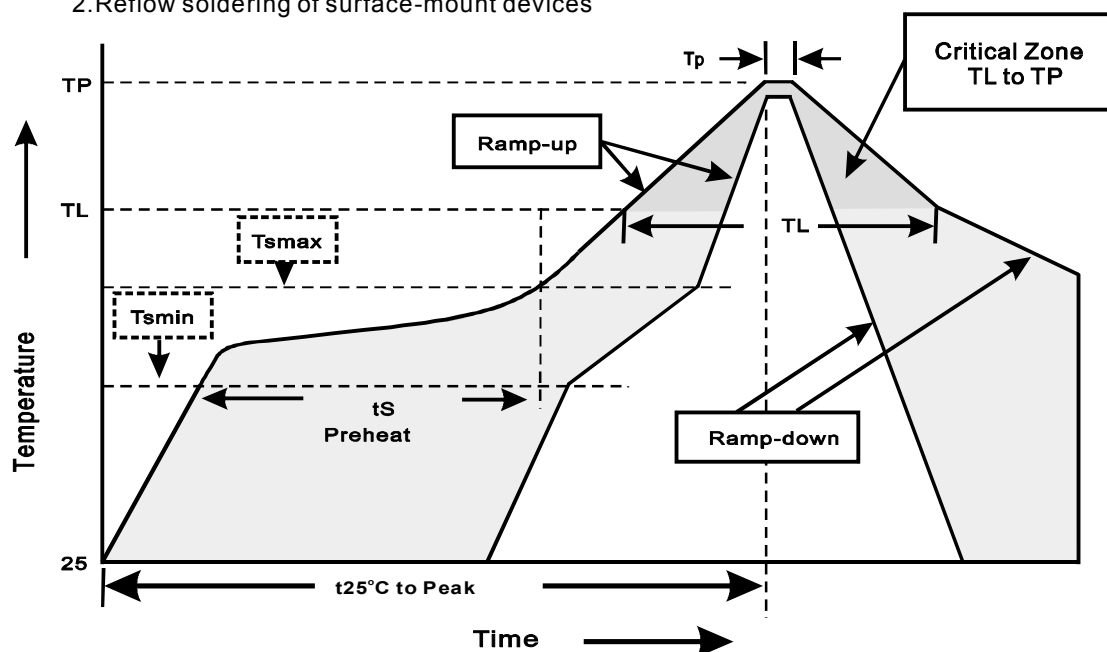
LL12BT1006

Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (m/m)	BOX (pcs)	INNER BOX (m/m)	REEL DIA, (m/m)	CARTON SIZE (m/m)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
T1006P2	7"	10,000	4.0	100,000	183*123*183	178	382*257*387	800,000	15.0

Suggested thermal profiles for soldering processes

- 1.Storage environment: Temperature=5°C~40°C Humidity=55%±25%
- 2.Reflow soldering of surface-mount devices



3.Reflow soldering

Profile Feature	Soldering Condition
Average ramp-up rate(T _L to T _P)	<3°C/sec
Preheat - Temperature Min(T _{smin}) - Temperature Max(T _{smax}) - Time(min to max)(t _s)	150°C 200°C 60~120sec
T _{smax} to T _L - Ramp-upRate	<3°C/sec
Time maintained above: - Temperature(T _L) - Time(t _L)	217°C 60~260sec
Peak Temperature(T _P)	255°C-0/+5°C
Time within 5°C of actual Peak Temperature(t _P)	10~30sec
Ramp-down Rate	<6°C/sec
Time 25°C to Peak Temperature	<6minutes